



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D

*\* : Required Field*

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2017-05-31
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	ADG MD CHAMPION
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**


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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
BAS70-05WFILM	HJUC*NHBAR28	A	Z55A	2017-05-31
	Amount	UoM	Unit type	ST ECOPACK Grade
	6.00	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Alloy 42		

Package Designator	Size	Nbr of instances	Shape	
SOT	1.8 X 1.15 X 0.8	3	gull wing	
Comment	Package: SOT 323 CATHODE COMMUNE 3L			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description

Query : California Prop65 list, dated 27th January 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	1.68	leadframe alloy	279167
Cobalt	0.01	leadframe alloy	1333

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	HIUC* NHBAR28					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	0.093	mg	supplier	die	Silicon (Si)	7440-21-3		0.088	mg	946237	14667
				supplier	metallization	Aluminium (Al)	7429-90-5		0.004	mg	43010	667
				supplier	Passivation	Silicon Oxide	7631-86-9		0.001	mg	10753	167
Leadframe	Other Ferrous alloys, non-stainless ste	1.675	mg	supplier	alloy	Manganese (Mn)	7439-96-5		0.010	mg	5970	1667
				supplier	alloy	Iron (Fe)	7439-89-6		0.930	mg	555224	155000
				supplier	alloy	Cobalt (Co)	7440-48-4		0.008	mg	4776	1333
				supplier	alloy	Silicon (Si)	7440-21-3		0.003	mg	1791	500
				supplier	alloy	Nickel (Ni)	7440-02-0		0.662	mg	395224	110333
				supplier	metallization	Silver (Ag)	7440-22-4		0.062	mg	37015	10333
Bonding wire	Precious metals	0.024	mg	supplier	wire	Gold (Au)	7440-57-5		0.024	mg	1000000	4000
Encapsulation	Other inorganic materials	3.994	mg	supplier	mold compound	silica vitreous	60676-86-0		3.408	mg	853280	568000
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		0.219	mg	54832	36500
				supplier	mold compound	Phenol Resin	26834-02-6		0.199	mg	49825	33167
				supplier	mold compound	Tetrakis(2,6-dimethylphenyl) 1,3-phenylene bi	139189-30-3		0.100	mg	25038	16667
				supplier	mold compound	Carbon black	1333-86-4		0.008	mg	2002	1332
Connections coating	Solder	0.214	mg	supplier	solder alloy	Biphenyl epoxy resin	85954-11-6		0.060	mg	15023	10000
				supplier	solder alloy	Tin (Sn)	7440-31-5		0.214	mg	1000000	35667